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### Dimensions

Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.9mm +/-0.10mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

### Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

### General Information

Series	SMD Comm X8L HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Temperature Stable
Features	High Temperature, Temperature Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	13 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	0.33 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15%/-40%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	1.5152 GOhms